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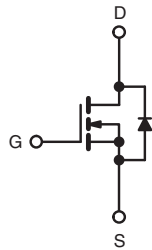
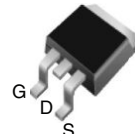
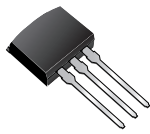




## Power MOSFET

| PRODUCT SUMMARY           |                            |
|---------------------------|----------------------------|
| $V_{DS}$ (V)              | 600                        |
| $R_{DS(on)}$ ( $\Omega$ ) | $V_{GS} = 10\text{ V}$ 2.2 |
| $Q_g$ (Max.) (nC)         | 23                         |
| $Q_{gs}$ (nC)             | 5.4                        |
| $Q_{gd}$ (nC)             | 11                         |
| Configuration             | Single                     |

I<sup>2</sup>PAK (TO-262) D<sup>2</sup>PAK (TO-263)



N-Channel MOSFET

### FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- Low Gate Charge  $Q_g$  Results in Simple Drive Requirement
- Improved Gate, Avalanche and Dynamic  $dV/dt$  Ruggedness
- Fully Characterized Capacitance and Avalanche Voltage and Current
- Effective  $C_{OSS}$  Specified
- Compliant to RoHS Directive 2002/95/EC



### APPLICATIONS

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply
- High Speed Power Switching

### TYPICAL SMPS TOPOLOGIES

- Single Transistor Flyback

| ORDERING INFORMATION            |                             |                                |                                |                             |
|---------------------------------|-----------------------------|--------------------------------|--------------------------------|-----------------------------|
| Package                         | D <sup>2</sup> PAK (TO-263) | D <sup>2</sup> PAK (TO-263)    | D <sup>2</sup> PAK (TO-263)    | I <sup>2</sup> PAK (TO-262) |
| Lead (Pb)-free and Halogen-free | SiHFBC30AS-GE3              | SiHFBC30ASTRL-GE3 <sup>a</sup> | SiHFBC30ASTRR-GE3 <sup>a</sup> | SiHFBC30AL-GE3              |
| Lead (Pb)-free                  | IRFBC30ASPbF                | IRFBC30ASTRLPbF <sup>a</sup>   | IRFBC30ASTRRPbF <sup>a</sup>   | IRFBC30ALPbF                |
|                                 | SiHFBC30AS-E3               | SiHFBC30ASTL-E3 <sup>a</sup>   | SiHFBC30ASTR-E3 <sup>a</sup>   | SiHFBC30AL-E3               |

#### Note

a. See device orientation.

| ABSOLUTE MAXIMUM RATINGS ( $T_C = 25\text{ }^\circ\text{C}$ , unless otherwise noted) |                                  |                                   |                  |                     |
|---|----------------------------------|-----------------------------------|------------------|---------------------|
| PARAMETER   | SYMBOL                           | LIMIT                             | UNIT             |                     |
| Drain-Source Voltage  | $V_{DS}$                         | 600                               | V                |                     |
| Gate-Source Voltage   | $V_{GS}$                         | $\pm 30$                          |                  |                     |
| Continuous Drain Current  | $V_{GS}$ at 10 V                 | $T_C = 25\text{ }^\circ\text{C}$  | 3.6              | A                   |
|   |                                  | $T_C = 100\text{ }^\circ\text{C}$ | 2.3              |                     |
| Pulsed Drain Current <sup>a, e</sup>  |                                  | $I_{DM}$                          | 14               |                     |
| Linear Derating Factor  |                                  |                                   | 0.69             | W/ $^\circ\text{C}$ |
| Single Pulse Avalanche Energy <sup>b</sup>  | $E_{AS}$                         | 290                               |                  | mJ                  |
| Avalanche Current <sup>a</sup>  | $I_{AR}$                         | 3.6                               |                  | A                   |
| Repetitive Avalanche Energy <sup>a</sup>  | $E_{AR}$                         | 7.4                               |                  | mJ                  |
| Maximum Power Dissipation   | $T_C = 25\text{ }^\circ\text{C}$ | $P_D$                             | 74               | W                   |
| Peak Diode Recovery $dV/dt$ <sup>c, e</sup>   |                                  | $dV/dt$                           | 7.0              | V/ns                |
| Operating Junction and Storage Temperature Range                                      | $T_J, T_{stg}$                   |                                   | - 55 to + 150    | $^\circ\text{C}$    |
| Soldering Recommendations (Peak Temperature)  | for 10 s                         |                                   | 300 <sup>d</sup> |                     |

#### Notes


- Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- Starting  $T_J = 25\text{ }^\circ\text{C}$ ,  $L = 46\text{ mH}$ ,  $R_g = 25\text{ }\Omega$ ,  $I_{AS} = 3.6\text{ A}$  (see fig. 12).
- $I_{SD} \leq 3.6\text{ A}$ ,  $dI/dt \leq 170\text{ A}/\mu\text{s}$ ,  $V_{DD} \leq V_{DS}$ ,  $T_J \leq 150\text{ }^\circ\text{C}$ .
- 1.6 mm from case.
- Uses IRFBC30A/SiHFBC30A data and test conditions.

\* Pb containing terminations are not RoHS compliant, exemptions may apply

| THERMAL RESISTANCE RATINGS   |            |      |      |      |
|--|------------|------|------|------|
| PARAMETER  | SYMBOL     | TYP. | MAX. | UNIT |
| Maximum Junction-to-Ambient (PCB Mounted, steady-state) <sup>a</sup> | $R_{thJA}$ | -    | 40   | °C/W |
| Maximum Junction-to-Case (Drain)                                     | $R_{thJC}$ | -    | 1.7  |      |

### Note

a. When mounted on 1" square PCB (FR-4 or G-10 material).

| SPECIFICATIONS ( $T_J = 25\text{ }^\circ\text{C}$ , unless otherwise noted) |                       |  |  |      |           |               |    |
|---|-----------------------|--|--|------|-----------|---------------|----|
| PARAMETER   | SYMBOL                | TEST CONDITIONS  | MIN.   | TYP. | MAX.      | UNIT          |    |
| <b>Static</b>   |                       |  |  |      |           |               |    |
| Drain-Source Breakdown Voltage  | $V_{DS}$              | $V_{GS} = 0, I_D = 250\text{ }\mu\text{A}$   | 600  | -    | -         | V             |    |
| $V_{DS}$ Temperature Coefficient  | $\Delta V_{DS}/T_J$   | Reference to $25\text{ }^\circ\text{C}$ , $I_D = 1\text{ mA}^d$  | -  | 0.67 | -         | V/°C          |    |
| Gate-Source Threshold Voltage   | $V_{GS(th)}$          | $V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$  | 2.0  | -    | 4.5       | V             |    |
| Gate-Source Leakage   | $I_{GSS}$             | $V_{GS} = \pm 30\text{ V}$   | -  | -    | $\pm 100$ | nA            |    |
| Zero Gate Voltage Drain Current   | $I_{DSS}$             | $V_{DS} = 600\text{ V}, V_{GS} = 0\text{ V}$   | -  | -    | 25        | $\mu\text{A}$ |    |
|   |                       | $V_{DS} = 480\text{ V}, V_{GS} = 0\text{ V}, T_J = 125\text{ }^\circ\text{C}$  | -  | -    | 250       |               |    |
| Drain-Source On-State Resistance  | $R_{DS(on)}$          | $V_{GS} = 10\text{ V}$   $I_D = 2.2\text{ A}^b$  | -  | -    | 2.2       | $\Omega$      |    |
| Forward Transconductance  | $g_{fs}$              | $V_{DS} = 50\text{ V}, I_D = 2.2\text{ A}$   | 2.1  | -    | -         | S             |    |
| <b>Dynamic</b>  |                       |  |  |      |           |               |    |
| Input Capacitance   | $C_{iss}$             | $V_{GS} = 0\text{ V}, V_{DS} = 25\text{ V}, f = 1.0\text{ MHz}$ , see fig. 5   | -  | 510  | -         | pF            |    |
| Output Capacitance  | $C_{oss}$             |  | -  | 70   | -         |               |    |
| Reverse Transfer Capacitance  | $C_{rss}$             |  | -  | 3.5  | -         |               |    |
| Output Capacitance  | $C_{oss}$             | $V_{GS} = 0\text{ V}$  | $V_{DS} = 1.0\text{ V}, f = 1.0\text{ MHz}$                                  | -    | 730       | -             |    |
| Effective Output Capacitance  | $C_{oss\text{ eff.}}$ |  | $V_{DS} = 480\text{ V}, f = 1.0\text{ MHz}$                                  | -    | 19        | -             |    |
| Total Gate Charge   | $Q_g$                 | $V_{GS} = 10\text{ V}$   | $I_D = 3.6\text{ A}, V_{DS} = 480\text{ V}$ , see fig. 6 and 13 <sup>b</sup> | -    | -         | 23            | nC |
| Gate-Source Charge  | $Q_{gs}$              |  |  | -    | -         | 5.4           |    |
| Gate-Drain Charge   | $Q_{gd}$              |  |  | -    | -         | 11            |    |
| Turn-On Delay Time  | $t_{d(on)}$           | $V_{DD} = 300\text{ V}, I_D = 3.6\text{ A}, R_g = 12\text{ }\Omega, R_D = 82\text{ }\Omega$ , see fig. 10 <sup>b, d</sup>                            | -  | 9.8  | -         | ns            |    |
| Rise Time   | $t_r$                 |  | -  | 13   | -         |               |    |
| Turn-Off Delay Time   | $t_{d(off)}$          |  | -  | 19   | -         |               |    |
| Fall Time   | $t_f$                 |  | -  | 12   | -         |               |    |
| <b>Drain-Source Body Diode Characteristics</b>                              |                       |  |  |      |           |               |    |
| Continuous Source-Drain Diode Current                                       | $I_S$                 | MOSFET symbol showing the integral reverse p - n junction diode  | -  | -    | 3.6       | A             |    |
| Pulsed Diode Forward Current <sup>a</sup>                                   | $I_{SM}$              |  | -  | -    | 14        |               |    |
| Body Diode Voltage  | $V_{SD}$              | $T_J = 25\text{ }^\circ\text{C}, I_S = 3.6\text{ A}, V_{GS} = 0\text{ V}^b$  | -  | -    | 1.6       | V             |    |
| Body Diode Reverse Recovery Time  | $t_{rr}$              | $T_J = 25\text{ }^\circ\text{C}, I_F = 3.6\text{ A}, di/dt = 100\text{ A}/\mu\text{s}^b$   | -  | 400  | 600       | ns            |    |
| Body Diode Reverse Recovery Charge  | $Q_{rr}$              |  | -  | 1.1  | 1.7       | $\mu\text{C}$ |    |
| Forward Turn-On Time  | $t_{on}$              | Intrinsic turn-on time is negligible (turn-on is dominated by $L_S$ and $L_D$ )  |  |      |           |               |    |

### Notes

- Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- Pulse width  $\leq 300\text{ }\mu\text{s}$ ; duty cycle  $\leq 2\%$ .
- $C_{oss\text{ eff.}}$  is a fixed capacitance that gives the same charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 to 80 %  $V_{DS}$ .
- Uses IRFBC30A/SiHFBC30A data and test conditions.



## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

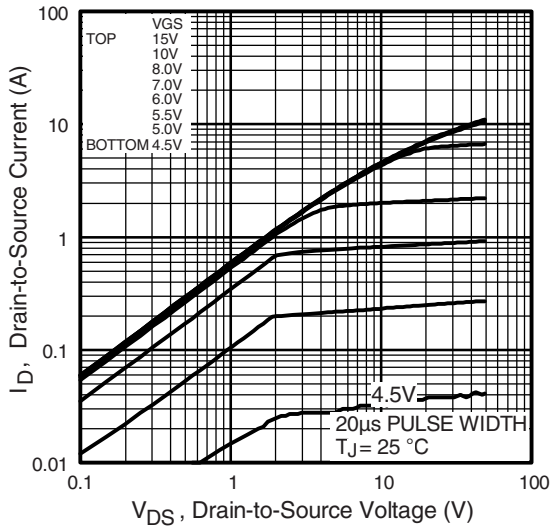


Fig. 1 - Typical Output Characteristics

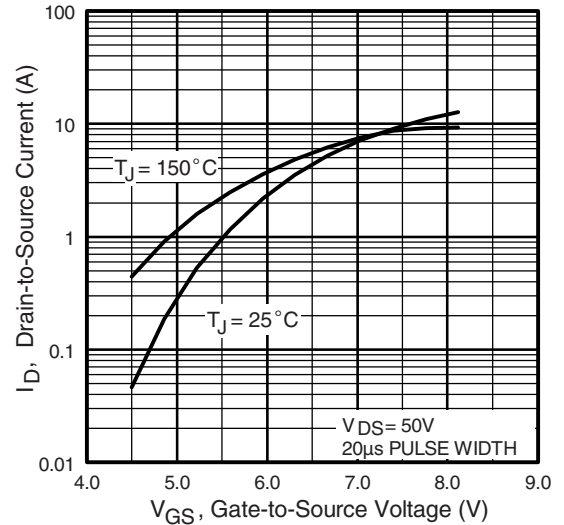


Fig. 3 - Typical Transfer Characteristics

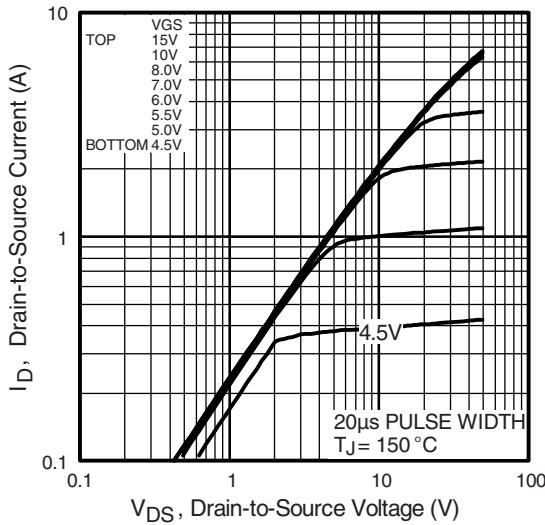


Fig. 2 - Typical Output Characteristics

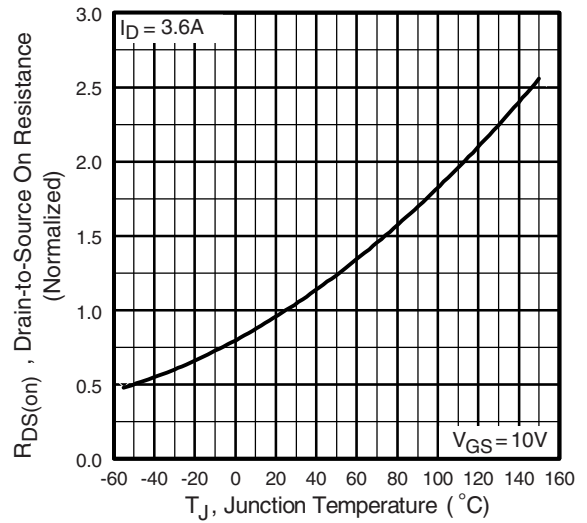


Fig. 4 - Normalized On-Resistance vs. Temperature

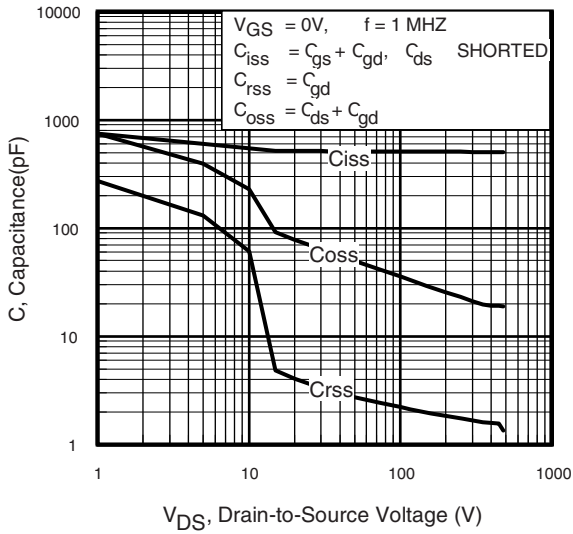


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

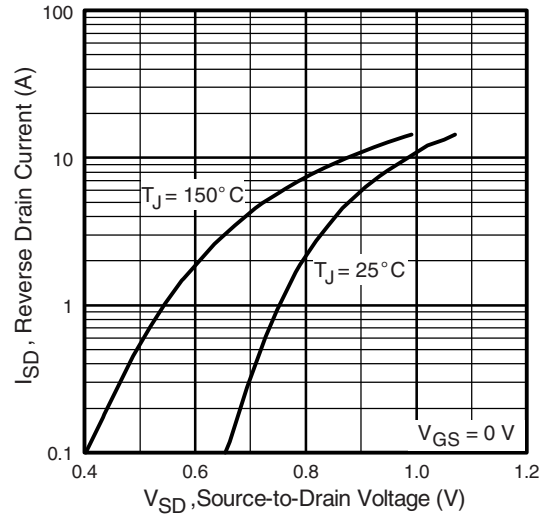


Fig. 7 - Typical Source-Drain Diode Forward Voltage

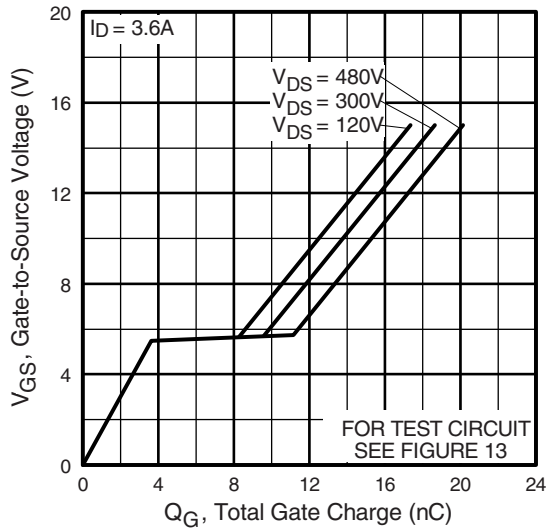


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

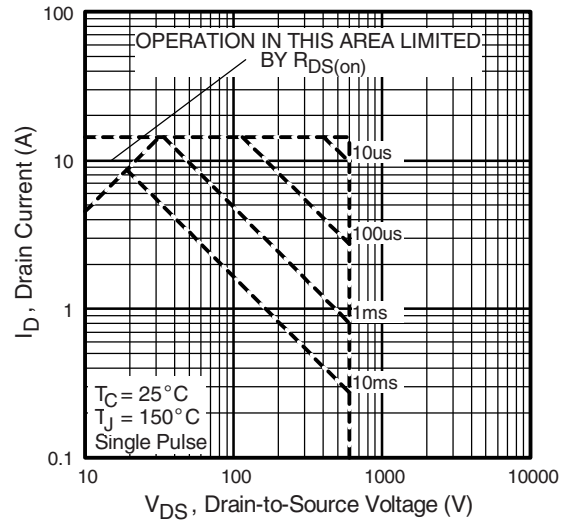
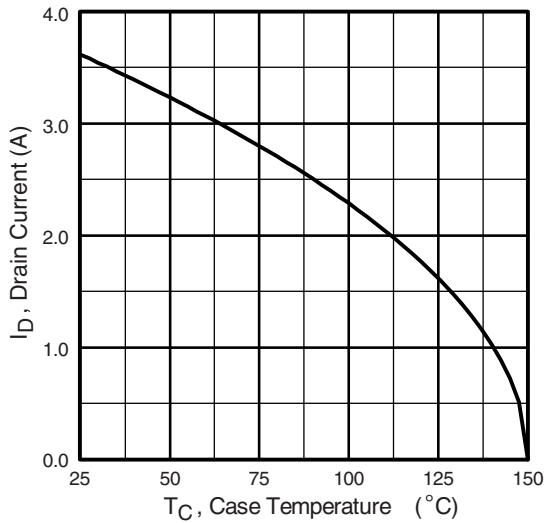
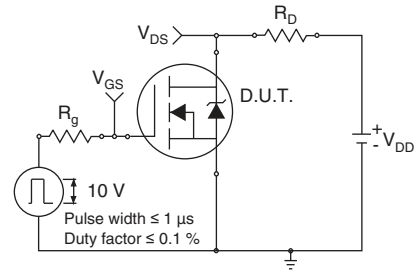


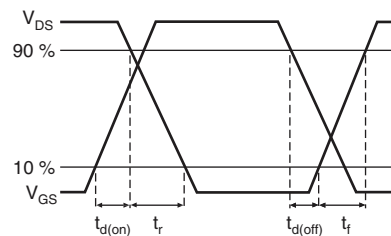
Fig. 8 - Maximum Safe Operating Area



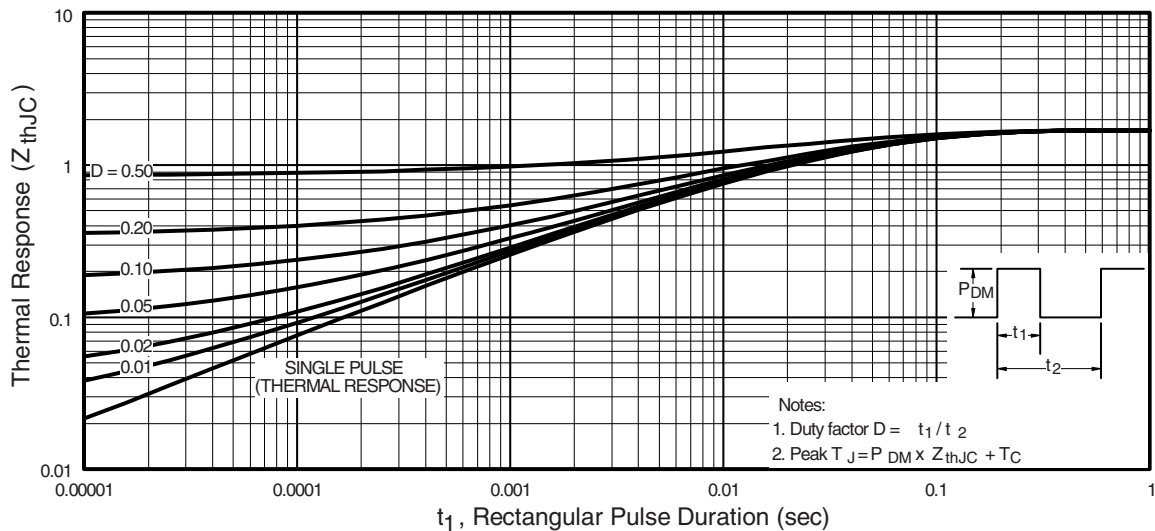
**Fig. 9 - Maximum Drain Current vs. Case Temperature**



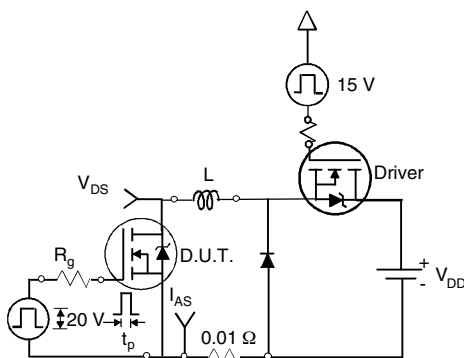
**Fig. 10a - Switching Time Test Circuit**



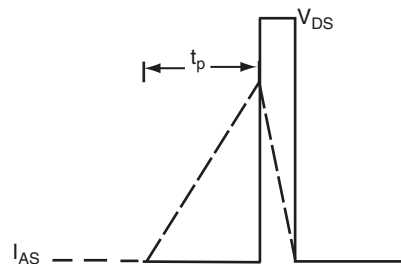
**Fig. 10b - Switching Time Waveforms**



**Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case**



**Fig. 12a - Unclamped Inductive Test Circuit**



**Fig. 12b - Unclamped Inductive Waveforms**

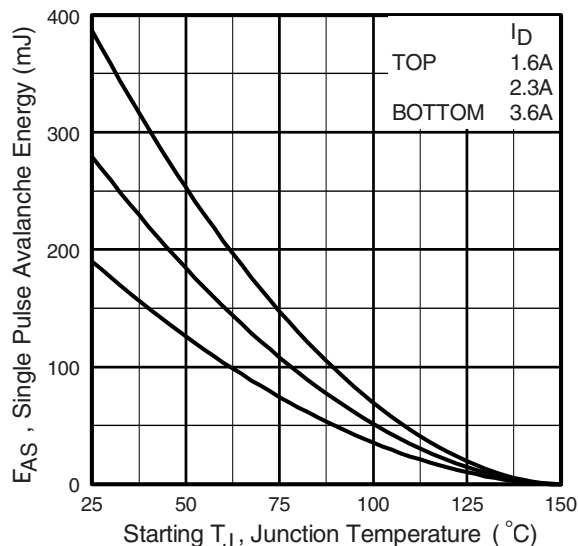


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

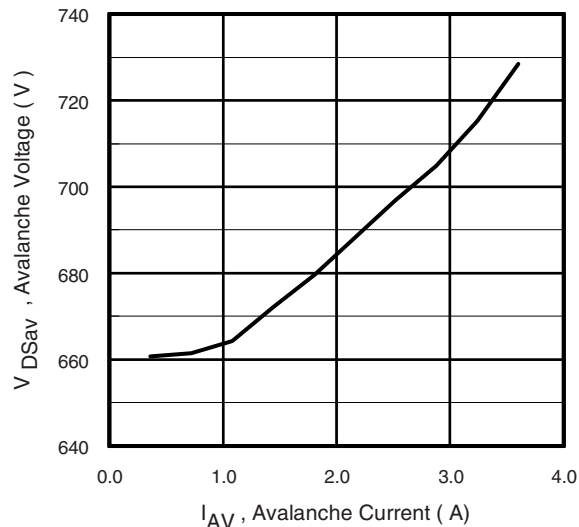


Fig. 12d - Typical Drain-to-Source Voltage vs. Avalanche Current

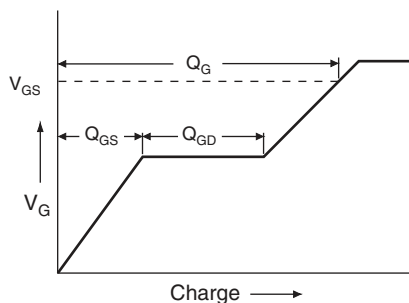


Fig. 13a - Basic Gate Charge Waveform

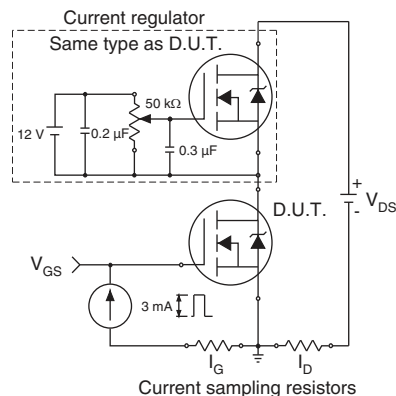
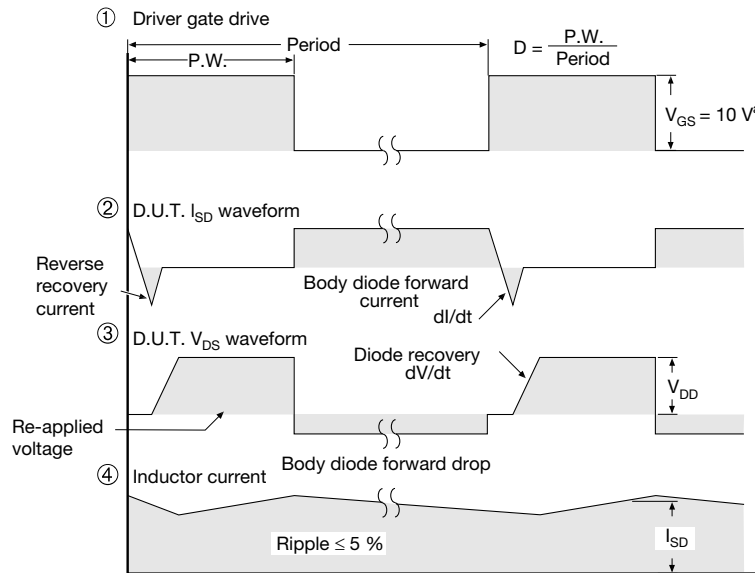
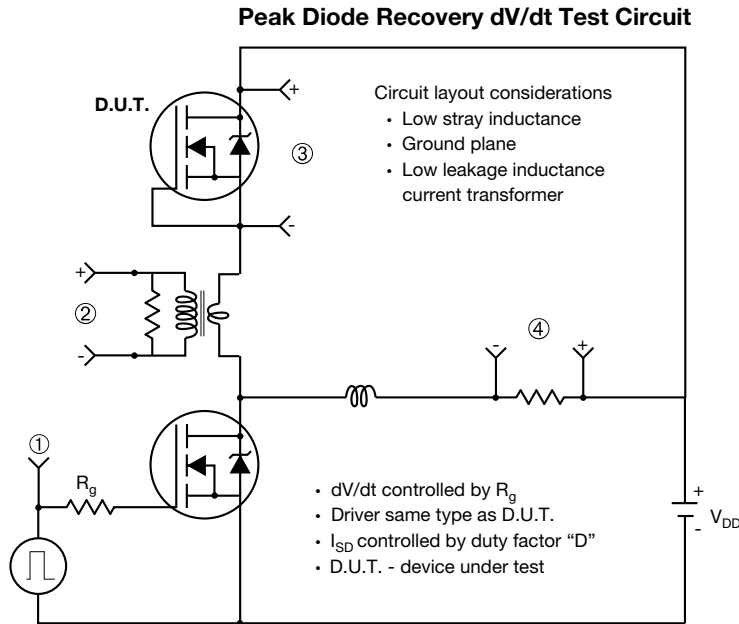


Fig. 13b - Gate Charge Test Circuit



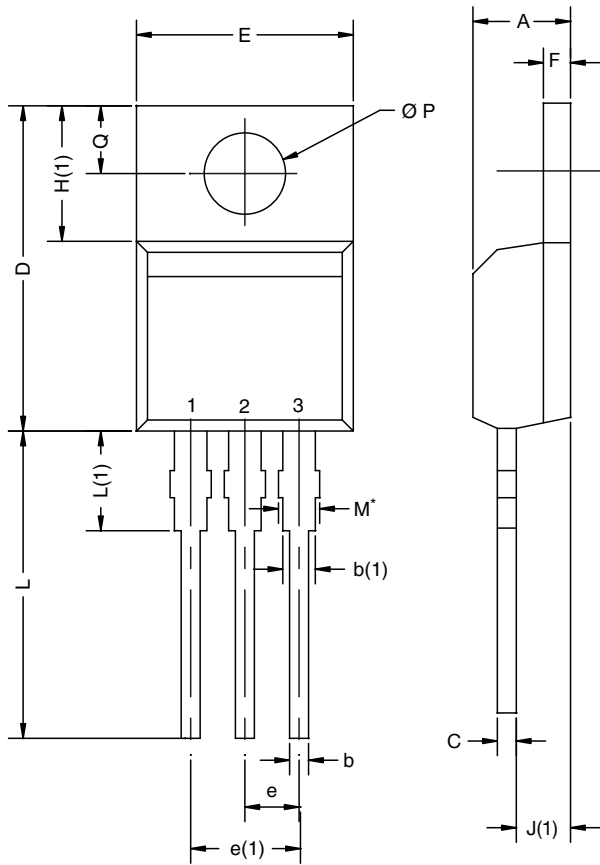
**Note**

a.  $V_{GS} = 5 V$  for logic level devices

**Fig. 14 - For N-Channel**

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## TO-220AB

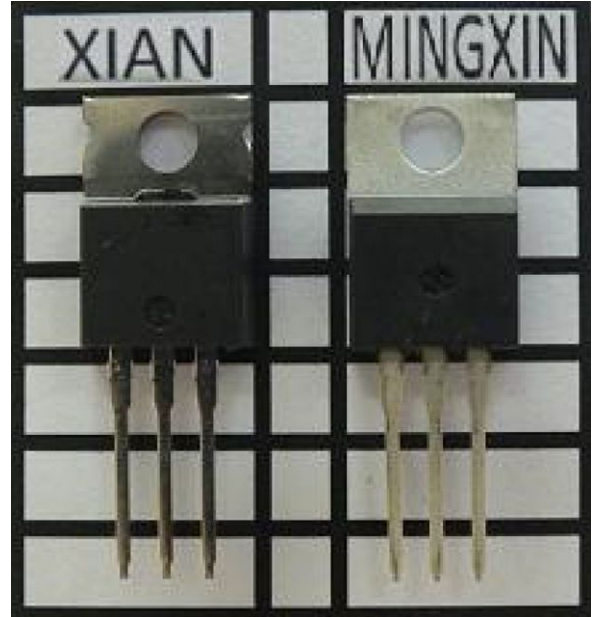


| DIM.            | MILLIMETERS |       | INCHES |       |
|-----------------|-------------|-------|--------|-------|
|                 | MIN.        | MAX.  | MIN.   | MAX.  |
| A               | 4.25        | 4.65  | 0.167  | 0.183 |
| b               | 0.69        | 1.01  | 0.027  | 0.040 |
| b(1)            | 1.20        | 1.73  | 0.047  | 0.068 |
| c               | 0.36        | 0.61  | 0.014  | 0.024 |
| D               | 14.85       | 15.49 | 0.585  | 0.610 |
| E               | 10.04       | 10.51 | 0.395  | 0.414 |
| e               | 2.41        | 2.67  | 0.095  | 0.105 |
| e(1)            | 4.88        | 5.28  | 0.192  | 0.208 |
| F               | 1.14        | 1.40  | 0.045  | 0.055 |
| H(1)            | 6.09        | 6.48  | 0.240  | 0.255 |
| J(1)            | 2.41        | 2.92  | 0.095  | 0.115 |
| L               | 13.35       | 14.02 | 0.526  | 0.552 |
| L(1)            | 3.32        | 3.82  | 0.131  | 0.150 |
| $\varnothing P$ | 3.54        | 3.94  | 0.139  | 0.155 |
| Q               | 2.60        | 3.00  | 0.102  | 0.118 |

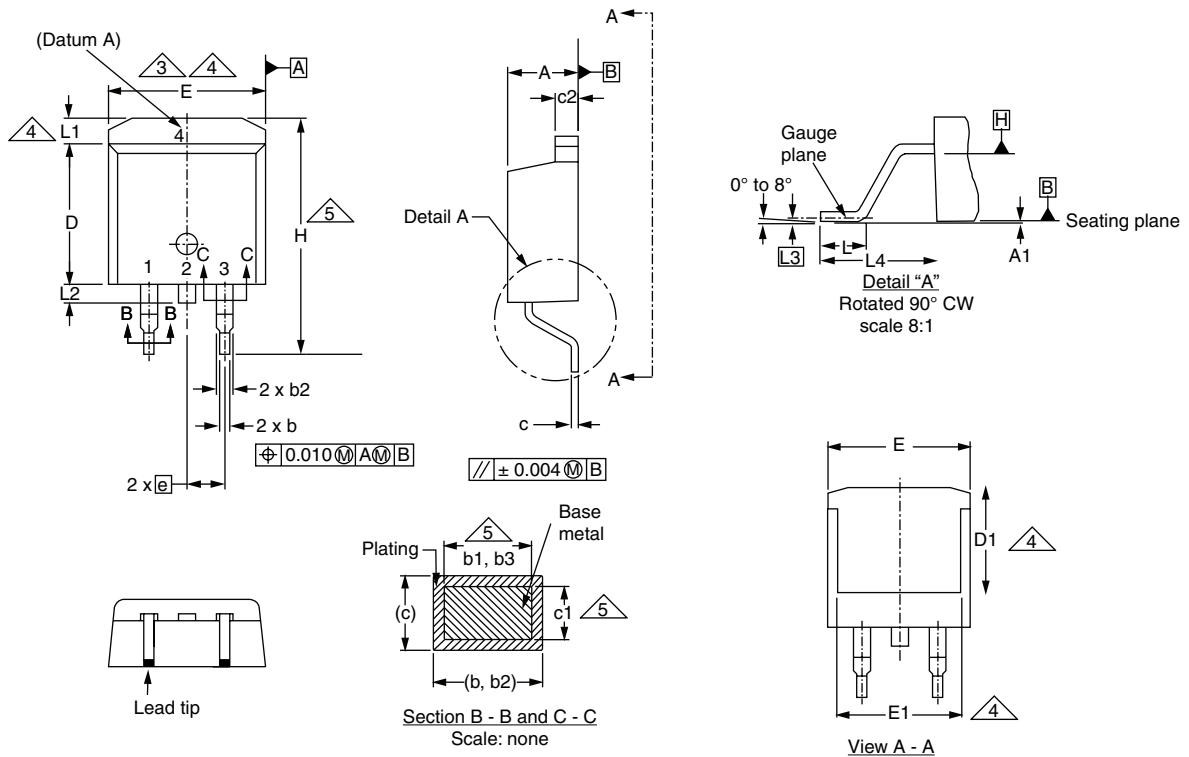
ECN: X12-0208-Rev. N, 08-Oct-12  
DWG: 5471

**Notes**

- \* M = 1.32 mm to 1.62 mm (dimension including protrusion)  
Heatsink hole for HVM
- Xi'an and Mingxin actual photo



### TO-263AB (HIGH VOLTAGE)



| DIM. | MILLIMETERS |      | INCHES |       |
|------|-------------|------|--------|-------|
|      | MIN.        | MAX. | MIN.   | MAX.  |
| A    | 4.06        | 4.83 | 0.160  | 0.190 |
| A1   | 0.00        | 0.25 | 0.000  | 0.010 |
| b    | 0.51        | 0.99 | 0.020  | 0.039 |
| b1   | 0.51        | 0.89 | 0.020  | 0.035 |
| b2   | 1.14        | 1.78 | 0.045  | 0.070 |
| b3   | 1.14        | 1.73 | 0.045  | 0.068 |
| c    | 0.38        | 0.74 | 0.015  | 0.029 |
| c1   | 0.38        | 0.58 | 0.015  | 0.023 |
| c2   | 1.14        | 1.65 | 0.045  | 0.065 |
| D    | 8.38        | 9.65 | 0.330  | 0.380 |

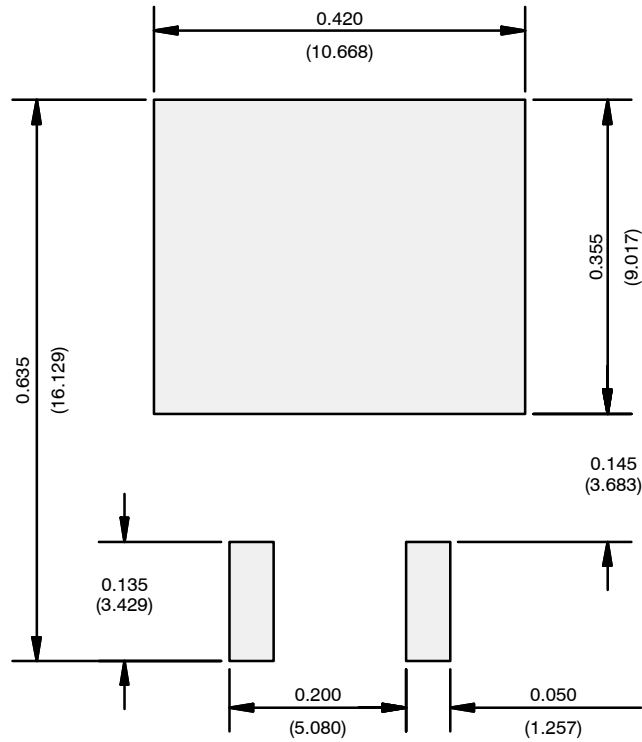
| DIM. | MILLIMETERS |       | INCHES    |       |
|------|-------------|-------|-----------|-------|
|      | MIN.        | MAX.  | MIN.      | MAX.  |
| D1   | 6.86        | -     | 0.270     | -     |
| E    | 9.65        | 10.67 | 0.380     | 0.420 |
| E1   | 6.22        | -     | 0.245     | -     |
| e    | 2.54 BSC    |       | 0.100 BSC |       |
| H    | 14.61       | 15.88 | 0.575     | 0.625 |
| L    | 1.78        | 2.79  | 0.070     | 0.110 |
| L1   | -           | 1.65  | -         | 0.066 |
| L2   | -           | 1.78  | -         | 0.070 |
| L3   | 0.25 BSC    |       | 0.010 BSC |       |
| L4   | 4.78        | 5.28  | 0.188     | 0.208 |

ECN: S-82110-Rev. A, 15-Sep-08  
DWG: 5970

#### Notes

1. Dimensioning and tolerancing per ASME Y14.5M-1994.
2. Dimensions are shown in millimeters (inches).
3. Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body at datum A.
4. Thermal PAD contour optional within dimension E, L1, D1 and E1.
5. Dimension b1 and c1 apply to base metal only.
6. Datum A and B to be determined at datum plane H.
7. Outline conforms to JEDEC outline to TO-263AB.

**RECOMMENDED MINIMUM PADS FOR D<sup>2</sup>PAK: 3-Lead**



Recommended Minimum Pads  
Dimensions in Inches/(mm)

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